Ridge-Width Dependence on High-Temperature Continuous-Wave Operation of Native Oxide-Confined InGaAsN Triple-Quantum-Well Lasers

C. Y. Liu, S. F. Yoon, W. J. Fan, A. Uddin, and S. Yuan

Abstract—InGaAsN triple-quantum-well (TQW) ridge waveguide (RWG) lasers were fabricated with contact ridge width of 4, 10, 50, and 100 μ m, respectively, using pulsed anodic oxidation (PAO). All these lasers worked under continuous-wave operation up to 100 °C. A clear trend of improved characteristic temperature (T_0) was observed as the ridge width narrowed. Proper choosing of ridge height and optimized PAO process were believed to minimize the lateral spreading current and reduce the scattering losses at the etched RWG sidewall, both of which are beneficial to the narrow ridge lasers operation. High output power of 298.8 mW, low transparency current density of 130 A/cm²/well, and high T_0 of 157.2 K were obtained from InGaAsN TQW 4- μ m-width lasers.

Index Terms—Characteristic temperature, InGaAsN, pulsed anodic oxidation (PAO), ridge waveguide (RWG) lasers.

I. INTRODUCTION

S INCE its first demonstration [1], InGaAsN quantum-well (QW) laser performance has been improved significantly [2]–[11]. In order to achieve efficient continuous-wave (CW) operation and low-cost systems, the operating current of In-GaAsN lasers must be low and insensitive to ambient temperature. In this sense, ridge waveguide (RWG) lasers would be desirable for their simple fabrication process, low threshold current ($I_{\rm th}$), and better heat dissipation, from which improvement of high-temperature operation could be expected [12], [14].

Ridge width (w) is an important factor that influences the RWG laser performance, which has been studied in several laser systems [12]–[15]. Usually, when w is reduced, the lateral spreading current (I_{Lateral}) within the conductive p-layers and scattering losses at the etched RWG sidewall will be increased, which are adverse to the laser performance [12]. In order to reduce w to smaller dimensions while minimizing the effects of I_{Lateral} and sidewall scattering, the ridge height (h) and fabrication process of RWG laser have to be carefully optimized. Though there have been several reports on high-performance InGaAsN RWG lasers [2]–[4], [8], as well as comprehensive study on the InGaAsN QW laser temperature sensitivity [11]; however, there is no study on the w effects of InGaAsN RWG



Fig. 1. CW *P*-*I* characteristics (20 °C-100 °C) of: (a) p-side down bonded InGaAsN laser ($w = 100 \ \mu$ m), the inset shows the room temperature, CW lasing spectrum; (b) p-side down bonded InGaAsN laser ($w = 50 \ \mu$ m); (c) unbonded InGaAsN laser ($w = 10 \ \mu$ m); (d) unbonded InGaAsN laser ($w = 4 \ \mu$ m), the inset shows a cross-sectional SEM image of an InGaAsN laser fabricated using PAO.

laser performance yet, especially on characteristic temperature (T_0) . In this letter, we report InGaAsN triple-QW (TQW) lasers, with different w while with the same optimum h, fabricated using optimized pulsed anodic oxidation (PAO) process.

II. EXPERIMENTAL DETAILS

InGaAsN TQW laser structures used in this work were grown using metal-organic chemical vapor deposition (MOCVD). The details of InGaAsN laser structure and optimization of fabrication process have been reported in [6] and [16]. Within the same process batch, four InGaAsN samples from the same wafer have been fabricated into lasers with different w of 100, 50, 10, and 4 μ m, respectively, with the same h of 1.23 μ m. Laser output power versus injection current (P-I) characteristics were measured from individual as-cleaved InGaAsN laser chips with different w and cavity length (L) under CW operation up to different temperature. For the study of w effects, L for all the lasers is fixed to 1500 μ m. Five lasers for each w were measured. Within a set of devices, the measured $I_{\rm th}$ was within $\pm 5\%$. The error bar was removed for clarity.

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C. Y. Liu, S. F. Yoon, and W. J. Fan are with the School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore (e-mail: liucy@ntu.edu.sg).

A. Uddin is with the School of Materials Science and Engineering, Nanyang Technological University, Singapore 639798, Singapore.

S. Yuan is with the Tinggi Technologies, Singapore 118258, Singapore. Digital Object Identifier 10.1109/LPT.2006.871697



Fig. 2. $\ln(I_{\rm th})$ versus T (20 °C-100 °C) from InGaAsN lasers with w of 4, 10, 50, and 100 μ m, respectively. The dots denote the experimental data and the lines are used for eye guidance. T_0 was calculated to be 157.2 K, 134 K, 130.6 K, and 124 K, respectively, in the linear region (20 °C-80 °C).

III. RESULTS AND DISCUSSION

Fig. 1(a), (b), (c), (d) shows the CW P-I characteristics (20 °C-100 °C) from InGaAsN TQW RWG lasers with different w. L and h for all the lasers are 1500 and 1.23 μ m, respectively. The inset of Fig. 1(a) shows the corresponding CW lasing spectrum, which is centered at 1297 nm, with the primary mode width $\Delta \lambda = 0.75$ nm. The inset of Fig. 1(d) shows a scanning electron microscope (SEM) cross-sectional image of the fabricated InGaAsN 4- μ m RWG laser, where the dark region is the pulsed anodic oxide formed in the PAO process.

Fig. 2 shows the plot of $\ln(I_{\rm th})$ versus device temperature (T) from InGaAsN lasers with different w. The dots denote the experimental data and the lines are used for eye guidance. Using (1), T_0 values (20 °C–80 °C) of each laser have been calculated to be 124 K ($w = 100 \ \mu m$), 130.6 K ($w = 50 \ \mu m$), 134 K ($w = 10 \ \mu m$), and 157.2 K ($w = 4 \ \mu m$), respectively. Obviously, T_0 is significantly higher for the InGaAsN laser with narrower w

$$I_{\rm th} = I_o \exp\left(\frac{T}{T_o}\right). \tag{1}$$

The "h" effects on transparency current density (J_{tr}) and external quantum efficiency (η_d) of RWG lasers have been reported in [6]. In order to study h effects on T_0 of the RWG lasers, CW P-I measurements (20 °C-80 °C) were also carried out on single-QW (SQW) InGaAs lasers with different h. Fig. 3(a) shows $I_{\rm th}$ versus T of InGaAs lasers ($w = 50 \ \mu {\rm m}$, $L = 1100 \ \mu \text{m}$) with different h. The inset shows the calculated J_{tr} [6] and T_0 as a function of h. It can be seen that the InGaAs laser with the optimized h of 1.23 μ m also has the highest T_0 of all the lasers, which is inconsistent with our previous study for the lowest J_{tr} and highest η_d [6]. Similarly, with reference to the InGaAsN laser structure [6], the optimum ridge height of 1.23 μ m, which corresponds to the removal of all the p-doped layers above the active region, is believed to be a reasonable compromise for maximizing the device performance, taking into consideration of I_{Lateral} and scattering losses at the sidewalls or exposed QW active region. In order to examine I_{Lateral} as w narrows, we plot I_{th} versus w from InGaAsN lasers in the temperature range of $20 \,^{\circ}\text{C} \sim 100 \,^{\circ}\text{C}$, as shown in Fig. 3(b). For clarity, only the data at 20 °C, 60 °C, 80 °C, and



Fig. 3. (a) $I_{\rm th}$ versus T (20 °C–80 °C) from a batch of InGaAs SQW lasers (50 × 1100 μ m²) with different h. The inset shows the calculated $J_{\rm tr}$ [6] and T_0 as a function of h. (b) $I_{\rm th}$ versus w from InGaAsN laser under temperature at 20 °C, 60 °C, 80 °C, 100 °C, respectively. The dots denote the experimental data and the lines are the best fit of the experimental data. The inset shows $J_{\rm th}$ versus w at different T for clarity.

100 °C are shown here. Following a model introduced by Letal *et al.* [13], the injection current (I_{in}) can be represented as

$$I_{\rm in}(w) = J_I \times L \times w + I_{\rm Leak}(w) \tag{2}$$

where J_I is the average recombination current density beneath the ridge; $I_{\text{Leak}}(w)$ is the lateral leakage current, which is controlled by three major processes: 1) I_{Lateral} within the conductive p-layers; 2) lateral diffusion current ($I_{\text{Diffusion}}$) in the QW and waveguide layer; and 3) losses at the etched RWG sidewalls [12]. In this work, we can neglect the sidewall scattering losses part due to the better passivation of optimized PAO process [16]. $I_{\text{Leak}}(w)$ can, therefore, be written as follows [13]:

$$I_{\text{Leak}}(w) = \frac{J_I \times L_C \times L_D \times \left(1 - e^{-\frac{w}{L_D}}\right)}{1 - \frac{L_D}{w} \times \left(1 - e^{-\frac{w}{L_D}}\right)}$$
(3)

where L_D is the diffusion length and represents the average distance that a carrier will diffuse before it recombines. Substituting (3) to (2), we can get

$$I_{\rm in}(w) = \frac{J_I \times L_C \times w}{1 - \frac{L_D}{w} \times \left(1 - e^{-\frac{w}{L_D}}\right)}.$$
(4)

From Fig. 3(b), the trend of $I_{\rm th}$ versus w is linear in the whole range. $I_{\rm Leak}(w)$ can be obtained by extrapolating to the zero active region width according to (2). From our work, $I_{\rm Leak}(w = 0)$ is small, in the range of 5–10 mA, and also is temperature insensitive. J_I and L_D can be obtained by fitting (4). In this



Fig. 4. P-I-V characteristics of a p-side down bonded InGaAsN laser (4 × 1600 μ m²). The inset shows $1/\eta_d$ versus L and $\ln(J_{\rm th})$ versus 1/L from a batch of InGaAsN RWG lasers. η_i and α_i were calculated to be 93.6% and 9.6 cm⁻¹, respectively; $J_{\rm tr}$ was calculated to be 389 A/cm².

work, L_D is in the range of 0.99–1.59 μ m, close to the reported hole diffusion length of 0.9 μ m in MOCVD-grown In-GaAsN material [17], which implied that hole diffusion may be dominant in the InGaAsN TQW lasers. For clarity, the inset of Fig. 3(b) shows $J_{\rm th}$ versus T from InGaAsN lasers with different w. $J_{\rm th}$ slightly increases as the w narrows but not as dramatically as reported in [14]. We believe the still remaining $I_{\text{Leak}}(w)$ (both I_{Lateral} and $I_{\text{Diffusion}}$) will become significant when w is small. Especially, when L_D is comparable to the ridge width, $I_{\text{Diffusion}}$ will become predominant in the narrow lasers. From Fig. 3(a) and (b), it can be seen that, with optimized h and PAO process, both I_{Lateral} and sidewall scattering losses were minimized. Therefore, low $I_{\rm th}$, and thus, low heat generation could be obtained from InGaAsN narrow RWG lasers. On the other hand, when the lasers get wider, it is likely there is significant thermal build up at the center under CW operation [15], which is detrimental to the high temperature operation. This can explain why narrow ridge RWG lasers, in our work, have significant higher T_0 .

InGaAsN 4- μ m RWG lasers have also been studied with different L in the range of 500 ~ 1500 μ m. Fig. 4 shows the CW power–current–voltage (P–I–V), at 20 °C of a p-side-down bonded InGaAsN TQW laser (4 × 1600 μ m²) fabricated using PAO. High output power around 298.8 mW/facet can be obtained from this device. The inset plots the relationship between η_d^{-1} versus L and ln(J_{th}) versus 1/L for the same batch of InGaAsN TQW 4- μ m RWG lasers. The internal optical loss (α_i) and internal quantum efficiency (η_i) is the 9.6 cm⁻¹ and 93.6%, respectively. The J_{tr} of the lasers was calculated to be 389 A/cm² (equivalent to 130 A/cm²/well) [18].

Compared with the published data [2]–[4], [8], above results are among the best for InGaAsN narrow RWG TQW lasers in the 1.29 $\sim 1.30 \ \mu m$ wavelength regime ever reported. We attributed the high performance of the narrow InGaAsN RWG lasers to the suppression of $I_{\rm Lateral}$ by optimization of h, reduced RWG sidewall loss due to optimized PAO process, and reduced heat generation of the narrow InGaAsN RWG lasers.

IV. CONCLUSION

InGaAsN TQW lasers were fabricated using PAO with different ridge width. With optimum h and optimized PAO process, $I_{\text{Leak}}(w)$ is small. Narrow ridge width (4 μ m) InGaAsN laser showed significant improved T_0 due to better heat dissipation. High output power of 298.8 mW/facet (4 × 1600 μ m²), low J_{tr} of 389 A/cm² (equivalent to 130 A/cm²/well) and high T_0 of 157.2 K were obtained from the InGaAsN TQW 4- μ m RWG lasers.

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